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ABSTRACT OF THE DISCLOSURE

A developer dispensing apparatus for dispensing developer solution onto a semiconductor wafer substrate which has a vertically-adjustable knife ring. The knife ring is vertically
5 actuated in the apparatus by pressurized air or fluid. In an application, the gap distance between the upper edge of the knife ring and the backside of the wafer is initially adjusted to a minimum value as the developer solution is dispensed onto the wafer, by adjusting the knife ring to the uppermost position in
10 the apparatus.